



DATA SHEET



MSP 2007

Peelable masking product

DESCRIPTION

MSP 2007 is a masking product which can be used when it is necessary to protect from solder. It is therefore extremely useful and advantageous in the soldering of printed circuits on automatic solder machines.

It is easily removed by peeling after soldering or cleaning.

PARTICULARITIES

- **MSP 2007** remaining opaque after polymerisation facilitates the pinpointing when peeling off and decreases the eye troubles when operating.
- It is neutral and suits specially to copper PCB
- It is no smell.
- The **MSP 2007** is suitable for the lead free soldering and dries quicker than the MSP 75.

METHOD OF USE

- Apply a thin coat of **MSP 2007**
- Allow to polymerise at room temperature for approximately 45 mn.
- Proceed with soldering.
- When the printed circuit board is cold, peel off the **MSP 2007**.
- In the event of dry oven polymerisation, the temperature should not exceed 60° C for a maximum period of 48 hours.
- Avoid prolonging the time between the polymerisation and the soldering, when the **MSP 2007** is in direct contact with copper.

PACKAGING

- 250 ml plastic bottles
- For other capacities : consult us

PHYSICAL PROPERTIES

- | | | | |
|---------------|-----------------|------------------|---|
| • Colour | White | • Solubility | in water before polymerisation |
| • Dry extract | 55 - 60 % | • Polymerisation | 45 mn (room temperature) according to deposit thickness |
| • Viscosity | 46,5 to 51 Pa.s | | |
| • pH | 7 | | |

SHELF LIFE

Under tests

STORAGE

Minimum temperature: 10° C

Maximum temperature: 30° C